

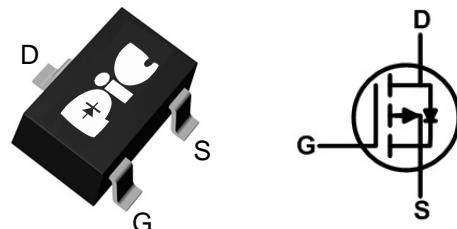
## ➤ General Description

This PAP2621NS P-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

## ➤ Feature

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- SOT-23S package design

## ➤ SOT-23S



## ➤ Application

- Load Switch
- Portable instrument
- MB / NB / 3C device

## ➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =25°C	-4.9	A
Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =70°C	-3.9	A
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	-14	A
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =25°C	1.31	W
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =70°C	0.84	W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	R <sub>θJA</sub>	120	°C/W
Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤10s)	R <sub>θJA</sub>	95	°C/W

➤ **Electrical Characteristics (T<sub>J</sub>=25°C Unless otherwise noted)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20	---	---	V
BV <sub>DSS</sub> Temperature Coefficient	△BV <sub>DSS</sub> /△T <sub>J</sub>	Reference to 25°C, I <sub>D</sub> =-1mA	---	-0.014	---	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.9A	---	40	45	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.4A	---	50	60	
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-2A	---	65	85	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA	-0.4	---	-1.0	V
V <sub>GS(th)</sub> Temperature Coefficient	△V <sub>GS(th)</sub>		---	3.95	---	mV/°C
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	-5	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	---	---	±100	nA
Forward Transconductance	g <sub>f</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A	---	12.8	---	S
Total Gate Charge (-4.5V)	Q <sub>g</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	---	10.2	14.3	nC
Gate-Source Charge	Q <sub>gs</sub>		---	1.89	2.6	
Gate-Drain Charge	Q <sub>gd</sub>		---	3.1	4.3	
Turn-On Delay Time	T <sub>d(on)</sub>	V <sub>DD</sub> =-10V, V <sub>GS</sub> =-4.5V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-3A	---	5.6	11.2	ns
Rise Time	T <sub>r</sub>		---	40.8	73	
Turn-Off Delay Time	T <sub>d(off)</sub>		---	33.6	67	
Fall Time	T <sub>f</sub>		---	18	36	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	---	857	1200	pF
Output Capacitance	C <sub>oss</sub>		---	114	160	
Reverse Transfer Capacitance	C <sub>rss</sub>		---	108	151	

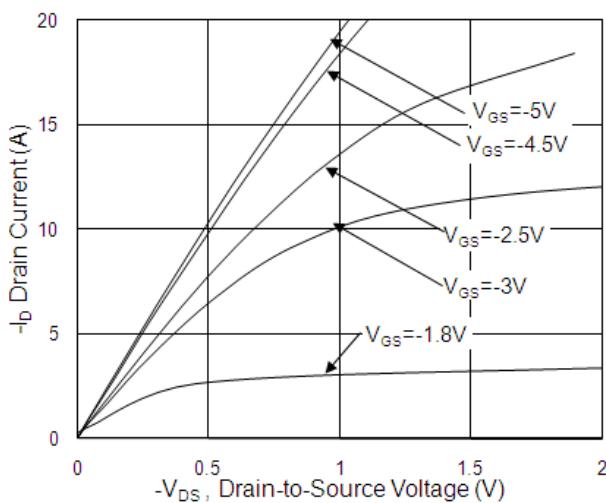
➤ **Diode Characteristics**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current <sup>1,4</sup>	I <sub>s</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-4.9	A
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1	V
Reverse Recovery Time	t <sub>rr</sub>	IF=-3A, di/dt=100A/μs, T <sub>J</sub> =25°C	---	21.8	---	nS
Reverse Recovery Charge	Q <sub>rr</sub>		---	6.9	---	nC

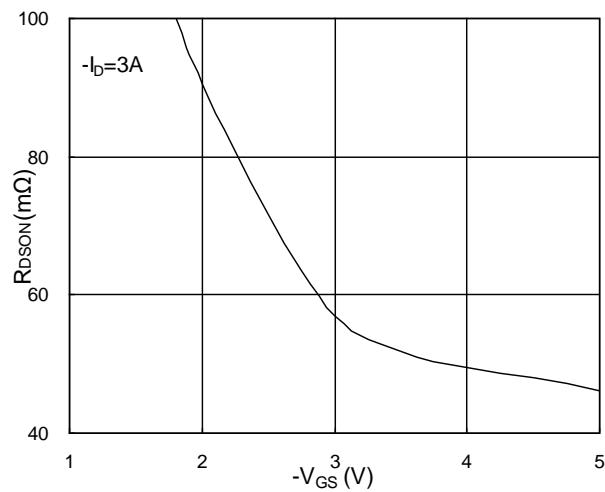
Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.Ensure that the channel temperature does not exceed 150°C.
- 4.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

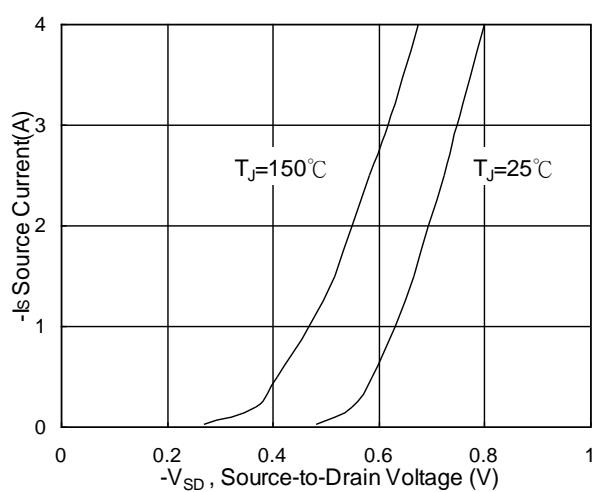
## ➤ Typical Characteristics



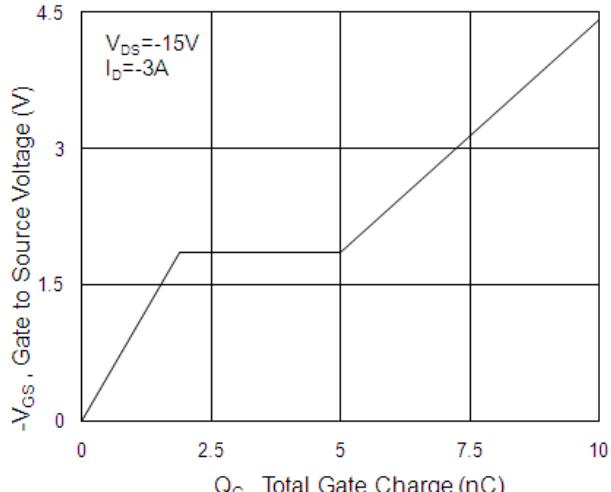
**Fig.1 Typical Output Characteristics**



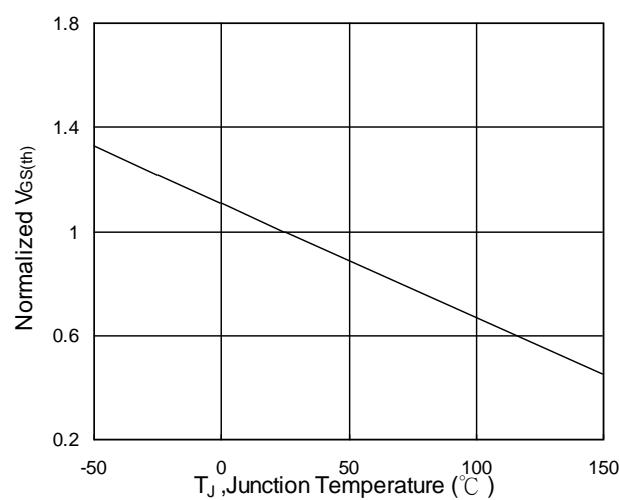
**Fig.2 On-Resistance vs. G-S Voltage**



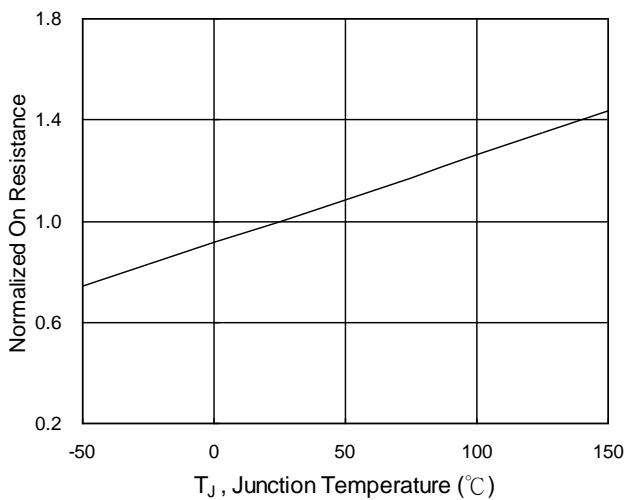
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-charge Characteristics**

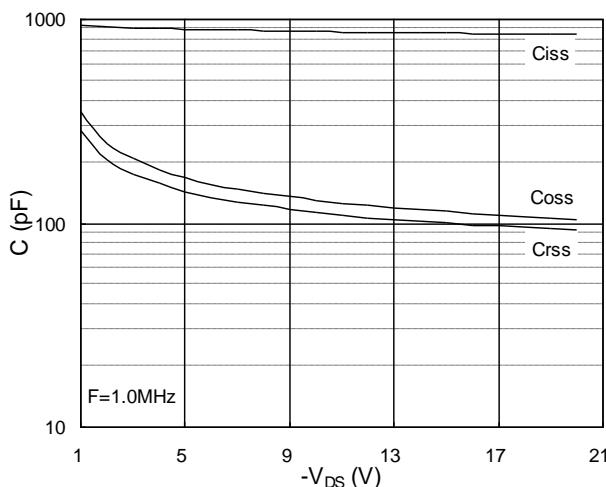


**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**

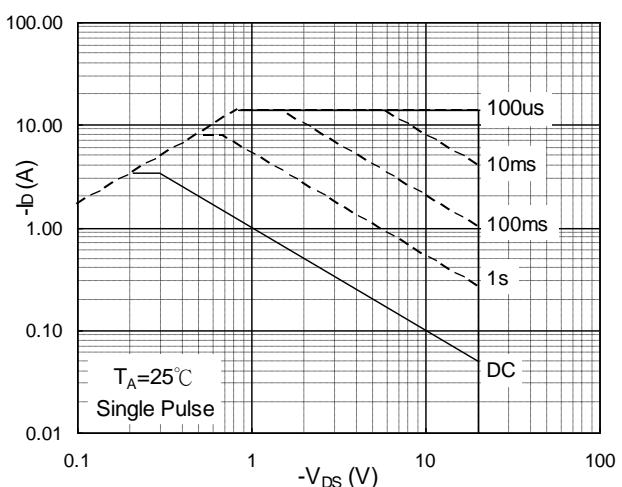


**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**

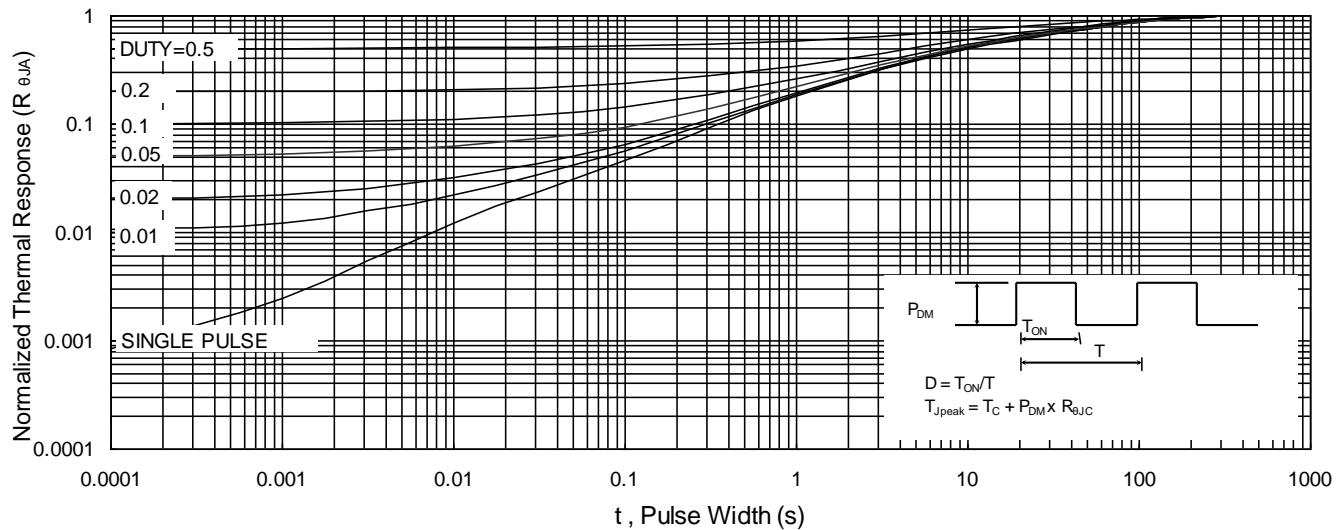
**P-Ch -20V Fast Switching MOSFET**  
**V<sub>DS</sub>=-20V, I<sub>D</sub>=-4.9A, R<sub>DS(ON)</sub>=45mΩ**



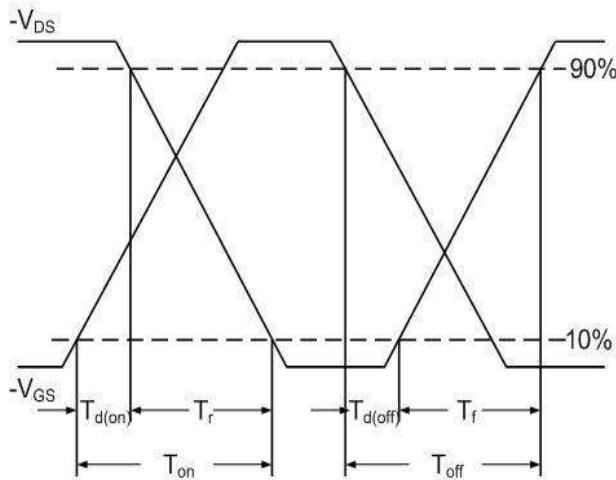
**Fig.7 Capacitance**



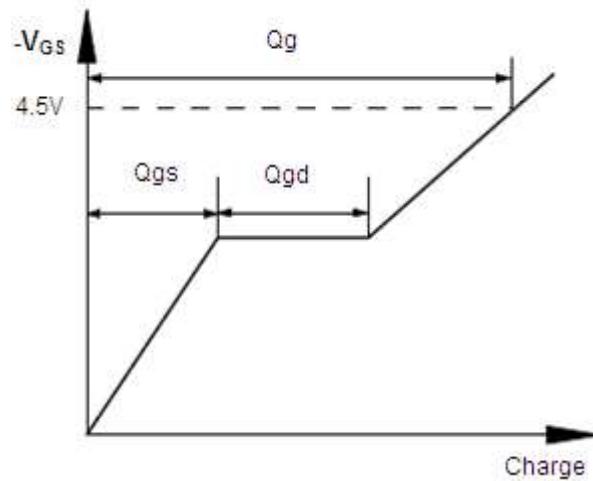
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

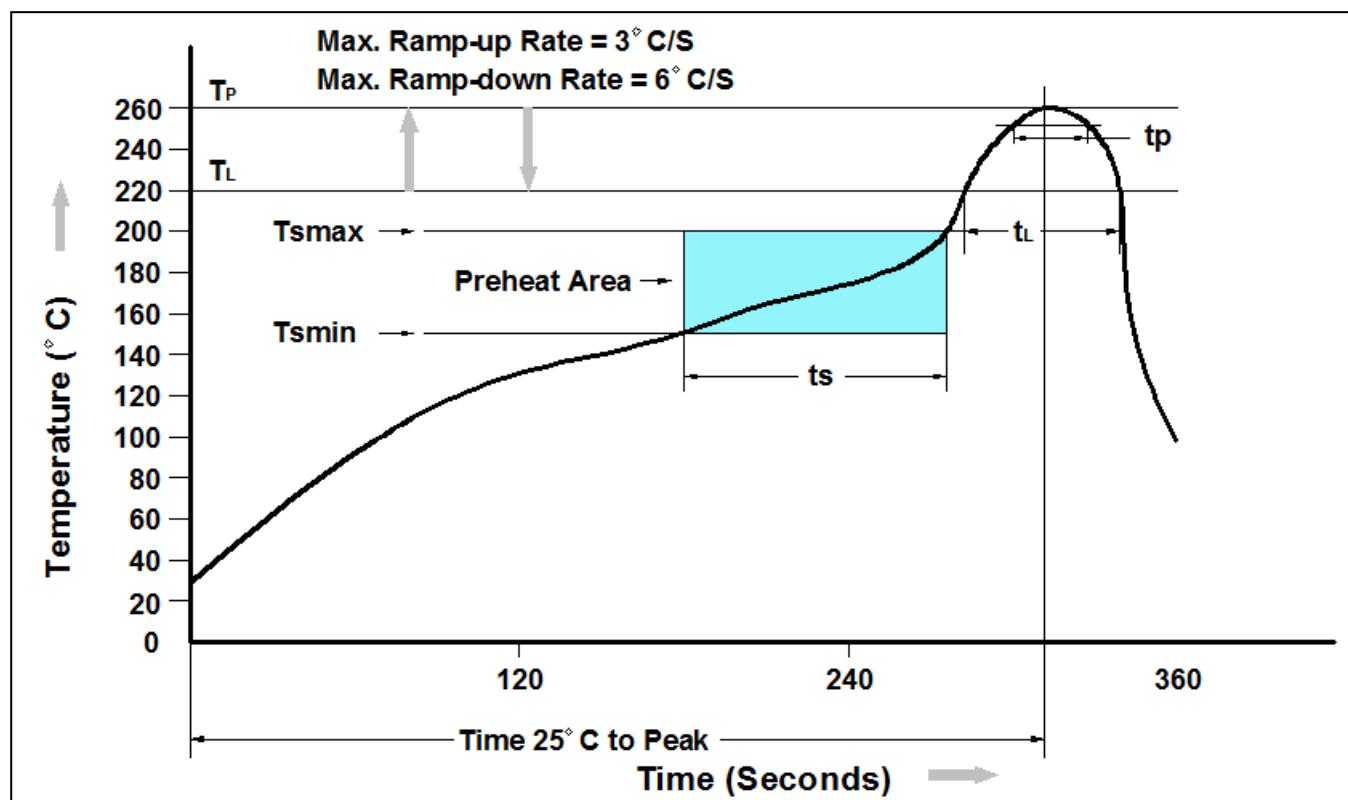


**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

➤ **Recommand IR Reflow Soldering Thermal Profile**

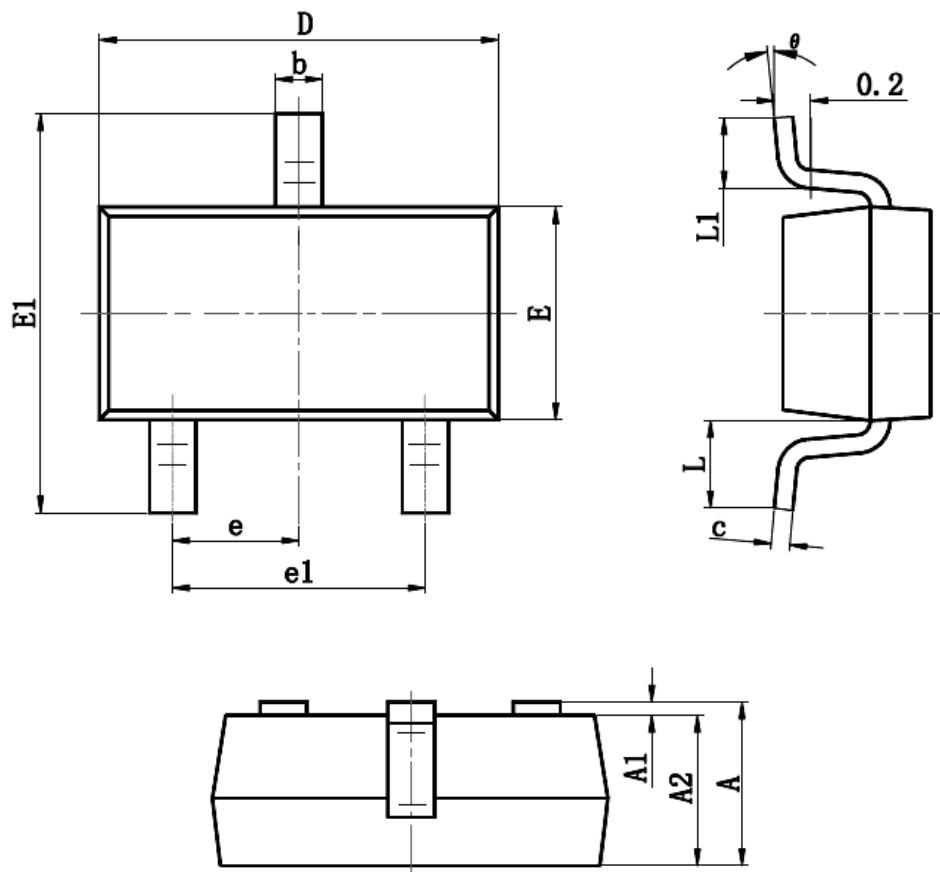


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds
Average Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ **Ordering Information**

Part Number	Description	Quantity
PAP2621NS	SOT-23S Reel	3000 pcs

➤ **Package Information ( SOT-23S )**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.200	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	6°

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